

(54) METHOD OF CONNECTION OF ELECTRONIC PARTS BY SOLDERING

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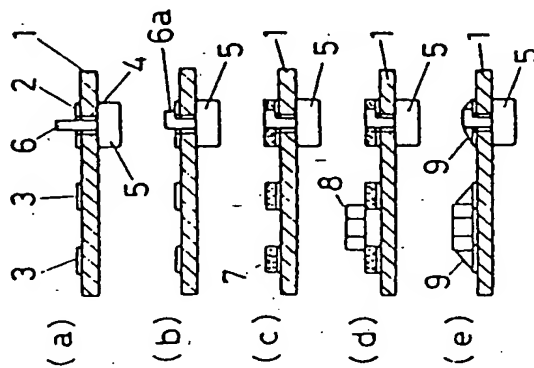
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PURPOSE: To make highly flexible the design, parts selection, and structure selection, keeping high productivity and high mounting density by mounting surface-mounting type electronic parts and insertion type electronic parts on the same wiring board, printing and supplying solder paste simultaneously through the same printing plate, and simultaneously performing reflow soldering.

CONSTITUTION: A lead wire 6 of insertion type electronic parts 5 is inserted into a lead wire insertion hole 4 in a printed board 1, and a portion of the tip end of the lead wire 6 protruding from a wiring board 1 surface is folded at a right angle so as to be parallel to the wiring board surface to provide a folded portion 6a. Then, solder paste 7 is printed on the lead wire tip end folded portion 6a and on a soldering land 6 for the surface mounting type electronic parts, simultaneously, and in succession the surface mounting type electronic parts 8 is mounted on the soldering paste 7 printed on the surface-mounting type electronic parts soldering land. Finally, the whole sample is held in an infrared furnace and a hot wind furnace, etc., to reflow the solder for yielding a soldered portion 9. Hereby, there are realized simultaneous printing of the soldering paste and simultaneous soldering by the reflow soldering.



LEGENDE zu den Bibliographiedaten

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